### PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Chia-Jung Li	03/19/2013
Chia-Jui Liang	03/19/2013
Po-Chao Tsao	03/19/2013
Ching-Ling Lin	03/19/2013
En-Chiuan Liou	03/19/2013

#### **RECEIVING PARTY DATA**

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13851113

### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	NAUP1618USA
NAME OF SUBMITTER:	SIBYL YU

Total Attachments: 10 source=1608283#page1.tif

PATENT REEL: 030092 FRAME: 0485 13851113

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PATENT REEL: 030092 FRAME: 0486

### Title of Invention:

### METHOD FOR FABRICATING PATTERNED STRUCTURE OF SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or	r			
☐ United States application nu	ımber	filed	on	_ , or
☐ PCT international applicatio	n number	fi	led on	
The above-identified application was	s made or authorized to	be made by me		
I believe that I am the original invent application.	or or an original joint in	ventor of a claim	ned invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				
In consideration of the payment by	UNITED MICROEL CORP.	ECTRONICS	having a postal a	ddress of
No.3, Li-Hsin Road 2, Science	e-Based Industrial	Park, Hsin-Ch	u City 300, Taiwa	ın, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are			e receipt of which is l	nereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, an	nd to any and all impro ation and, in and to, all r any continuations, co	vements which a Letters Patent to ntinuation-in-part	are disclosed in the be obtained for said t, divisions, renewals	,
I hereby covenant that no assignme entered into which would conflict wit		encumbrance ha	s been or will be mad	de or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letters F estify as to the same in	Patent and legal any interference	equivalents as may b , litigation proceeding	е
representatives any and all papers, maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	plication, said inventior ecessary or desirable to	and said Letters carry out the pr	s Patent and said oposes thereof.	e of signing)
Note: An application data sheet (PT)				

Page 1 of 10

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Chia-Jung Li

Date:

MAR 1 9 2013

Signature:

Chia-Jung Li

Page 2 of 10

F#NPO-P0002E-US1201 DSC0-102U000770

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377

PATENT REEL: 030092 FRAME: 0488

### Title of Invention:

# METHOD FOR FABRICATING PATTERNED STRUCTURE OF SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	ımber	filed	on	, or
☐ PCT international applicatio	n number	file	ed on	
The above-identified application was	made or authorized	o be made by me.		
I believe that I am the original invent application.	or or an original joint i	nventor of a claime	ed invention in	ı the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				le
In consideration of the payment by	UNITED MICROE	LECTRONICS	having a po	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-Ch	u City 300, 1	Гаiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar			receipt of wh	ich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, an	nd to any and all impr ition and, in and to, al r any continuations, c	ovements which ar Letters Patent to ontinuation-in-part,	re disclosed in be obtained fo divisions, ren	n the or said newals,
I hereby covenant that no assignmentered into which would conflict with		encumbrance has	been or will b	oe made or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exe	ntion and said Letters estify as to the same i	Patent and legal en any interference,	quivalents as litigation proc	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	olication, said invention ecessary or desirable	n and said Letters to carry out the pro	Patent and sa	
Note: An application data sheet (PT) inventive entity, must accompany this				

Page 3 of 10

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Chia-Jui Liang	Date:	MAR 19 2013		
Signature:	Chin - Ju broug				

Page 4 of I

4 of 10 F#NPO-P0002E-US1201 DSC0-102U000770

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377

### Title of Invention:

### METHOD FOR FABRICATING PATTERNED STRUCTURE OF SEMICONDUCTOR DEVICE

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☐ United States application nu	ımber	_filed o	n	, or
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I believe that I am the original invente application.	or or an original joint inventor of a	a claime	d invention in	the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri				9
In consideration of the payment by	UNITED MICROELECTROI CORP.	NICS	having a po	stal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	in-Chu	City 300, T	aiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		00), the i	receipt of whi	ch is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements wation and, in and to, all Letters Par r any continuations, continuation-	vhich are tent to b in-part, o	e disclosed in e obtained fo divisions, rene	the r said ewals,
I hereby covenant that no assignment entered into which would conflict with		nce has	been or will b	e made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interfe	legal eq erence, l	uivalents as i itigation proce	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said ecessary or desirable to carry out	Letters F the prop	Patent and sa poses thereof	
Note: An application data sheet (PTC				

Page 5 of 10

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Po-Chao Tsao

Date:

MAR 19 2013

Signature:

to hav Jean

Page 6 of 10

F#NPO-P0002E-US1201 DSC0-102U000770

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377

> PATENT REEL: 030092 FRAME: 0492

#### Title of Invention:

# METHOD FOR FABRICATING PATTERNED STRUCTURE OF SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	ımber	filed	on	, or
☐ PCT international application number filed on				
The above-identified application was	made or authorized	to be made by me.		
I believe that I am the original invente application.	or or an original joint	inventor of a claim	ed invention in	the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri				•
In consideration of the payment by	UNITED MICROR	ELECTRONICS	having a po	stal address of
No.3, Li-Hsin Road 2, Science	-Based Industria	ıl Park, Hsin-Chı	u City 300, T	aiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One ad valuable considera	Dollar (\$ 1.00), the ation.	receipt of whi	ch is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all imp tion and, in and to, a any continuations, o	rovements which and Ill Letters Patent to continuation-in-part,	re disclosed in be obtained for divisions, rene	the r said ewals,
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement on this assignment;	or encumbrance has	been or will b	e made or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exe-	ition and said Letters stify as to the same	s Patent and legal e in any interference,	quivalents as r litigation proce	nay be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention cessary or desirable	on and said Letters to carry out the pro	Patent and sale	id (Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi				

Page 7 of 10

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Ching-Ling Lin	Date:	MAR 19 2013			
Signature:	Ching-Ling Crn.					
	$\supset$ $\supset$					

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377 Page 8 of 10

F#NPO-P0002E-US1201 DSC0-102U000770

PATENT REEL: 030092 FRAME: 0494

### Title of Invention:

### METHOD FOR FABRICATING PATTERNED STRUCTURE OF SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	ımber	filed on	, or
☐ PCT international applicatio	n number	filed on	
The above-identified application was	made or authorized to be ma	ade by me.	
I believe that I am the original invent application.	or or an original joint inventor	of a claimed invention in t	the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
In consideration of the payment by	UNITED MICROELECTI	RONICS having a pos	tal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park,	Hsin-Chu City 300, Ta	aiwan, R.O.C.
(referred to as "ASSIGNEE" below) to acknowledged, andfor other good ar		\$ 1.00), the receipt of whic	:h is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application of substitutes, or extensions thereof, an	nd to any and all improvemer tion and, in and to, all Letters r any continuations, continuat	nts which are disclosed in t s Patent to be obtained for tion-in-part, divisions, rene	the said wals,
I hereby covenant that no assignmentered into which would conflict with		brance has been or will be	e made or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will terelated thereto and will promptly exe	ntion and said Letters Patent estify as to the same in any in	and legal equivalents as materierence, litigation proces	nay be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	olication, said invention and secessary or desirable to carry	aid Letters Patent and said out the proposes thereof.	
Note: An application data sheet (PT0 inventive entity, must accompany thi			

Page 9 of 10

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

**En-Chiuan Liou** 

Date:

MAR 19 2013

Signature:

En Opin an Lion

NPO#NAU-P1618-USA:0 CUST#UMCD-2012-0377 Page 10 of 10

F#NPO-P0002E-U\$1201 DSC0-102U000770

PATENT REEL: 030092 FRAME: 0496

**RECORDED: 03/27/2013**